

**REMARKS**

Claims 1-6 are pending in this application. By this Amendment, claim 1 and the drawings are amended.

The Office Action objects to the drawings. Figs. 1 and 2 are amended to be designated by a legend "related art" as the Examiner requested. Accordingly, withdrawal of the objection to the drawings is respectfully requested.

The Office Action rejects claims 1-4 under 35 U.S.C. §103(a) over Admitted Applicant Prior Art (AAPA) in view of U.S. Patent No. 5,981,036 to Schulz-Harder et al. ("Schulz-Harder"). This rejection is respectfully traversed.

The Office Action acknowledges that AAPA does not disclose a step of arranging short sides of element chips along a curving direction of a second substrate, as recited in claim 1, but asserts that Schulz-Harder discloses this feature. However, one of ordinary skill in the art would not have been motivated to combine Schulz-Harder with AAPA.

Schulz-Harder discloses a substrate 1 having a curved ceramic plate 2 with metal coatings 3 and 4 provided on both surface sides of the ceramic layer 2. See Fig. 1 and col. 2, lines 38-45. Schulz-Harder discloses that such a configuration allows for improved heat dissipation. See col. 1, lines 53-57. Schulz-Harder is not related to transferring functional elements from one substrate to another substrate. The AAPA and Schulz-Harder do not recognize the problem associated with the functional elements that are peeled off from a substrate. Thus, one of ordinary skill in the art would not have been motivated to combine Schulz-Harder with AAPA.

Furthermore, the AAPA and Schulz-Harder, even if combined, do not disclose or suggest the subject matter recited in claim 1, for at least the following two reasons.

First, the AAPA merely discloses that a functional element 14 is peeled from the first substrate 11. The AAPA does not disclose peeling the second substrate 21. Therefore, the

AAPA does not disclose or suggest transferring element chips on to the second flexible substrate peeled from the first substrate, as recited in claim 1.

Schulz-Harder discloses improving heat dissipation. Schulz-Harder does not disclose or suggest peeling a second substrate from a first substrate. Therefore, Schulz-Harder does not disclose or suggest transferring element chips on to the second flexible substrate peeled from the first substrate. Therefore, Schulz-Harder does not supply the subject matter lacking in the AAPA.

Second, the Office Action asserts that Schulz-Harder discloses, based on the language of claim 16 of Schulz-Harder, arranging short sides of element chips along a curving direction of the second substrate, as recited in claim 1. However, the "axis of curvature" of claim 16 of Schulz-Harder is parallel to the axis Q. See Fig. 2 and col. 2, lines 46-59. Thus, by requiring that the axis of curvature runs parallel to shorter sides of the rectangular pattern, the language of claim 16 requires the shorter sides to be lined with axis Q in Fig. 2. This requirement does not disclose the above quoted "arranging" limitation, because the "arranging" limitation recited in claim 1 of the present application requires that the short sides of the functional elements to be arranged along a curving direction which would be perpendicular to the axis Q of Schulz-Harder.

In view of the above, Schulz-Harder does not disclose or suggest transferring element chips from the second flexible substrate peeled from the first substrate; or arranging short sides of the element chips along a curving direction of the second substrate, as recited in claim 1. Therefore, Schulz-Harder does not supply the subject matter lacking in AAPA. Hence, the AAPA and Schulz-Harder, even if combined, do not disclose or suggest the subject matter recited in claim 1, and claims 2-4 depending therefrom.

For any or all of the above reasons, withdrawal of the rejection of claims 1-4 under 35 U.S.C. §103(a) is respectfully requested.

The Office Action rejects claims 5 and 6 under 35 U.S.C. §103(a) over the APPA in view of Schulz-Harder and further in view of U.S. Patent No. 6,261,881 to Yamazaki et al. This rejection is respectfully traversed.

Yamazaki discloses a semiconductor element that is capable of improving characteristics of a thin-film transistor "TFT". See col. 2, lines 41-49. Yamazaki does not disclose or suggest transferring element chips from the second flexible substrate peeled from the first substrate; or arranging short sides of element chips along a curving direction of a second substrate, as recited in claim 1. Therefore, Yamazaki does not supply the subject matter lacking in the APPA and Schulz-Harder.

Furthermore, as discussed above, one of ordinary skill in the art would not have been motivated to combine Schulz-Harder with the APPA. Therefore, one of ordinary skill in the art would not have been motivated to further combine Yamazaki.

For any or all of the above reasons, withdrawal of the rejection of claims 5 and 6 under 35 U.S.C. §103(a) is respectfully requested.

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of claims 1-6 are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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Attachment:  
Replacement Sheets

Date: August 2, 2005

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